



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Integrated Power Hybrid IC for
 Appliance Motor Drive Applications.

Description

International Rectifier's IRAMX16UP60A is an Integrated Power Module developed and optimized for electronic motor control in appliance applications such as washing machines and variable speed compressor drives for in-room air-conditioning systems and commercial refrigerators. Plug N Drive technology offers an extremely compact, high performance AC motor-driver in a single isolated package for a very simple design. An open emitter configuration of the low side IGBT switches offer easy current feedback and overcurrent monitor for high precision and reliable control.

A built-in temperature monitor and over-current protection, along with the short-circuit rated IGBTs and integrated under-voltage lockout function, deliver high level of protection and fail-safe operation.

The integration of the bootstrap diodes for the high-side driver section, and the single polarity power supply required to drive the internal circuitry, simplify the utilization of the module and deliver further cost reduction advantages.

Features

- Integrated Gate Drivers and Bootstrap Diodes.
- Temperature Monitor
- Temperature and Overcurrent shutdown
- Fully Isolated Package.
- Low VCE (on) Non Punch Through IGBT Technology.
- Undervoltage lockout for all channels
- Matched propagation delay for all channels
- Low side IGBT emitter pins for current control
- Schmitt-triggered input logic
- Cross-conduction prevention logic
- Lower di/dt gate driver for better noise immunity
- Motor Power range 0.75~2kW / 85~253 Vac
- Isolation 2000V_{RMS} min



Absolute Maximum Ratings

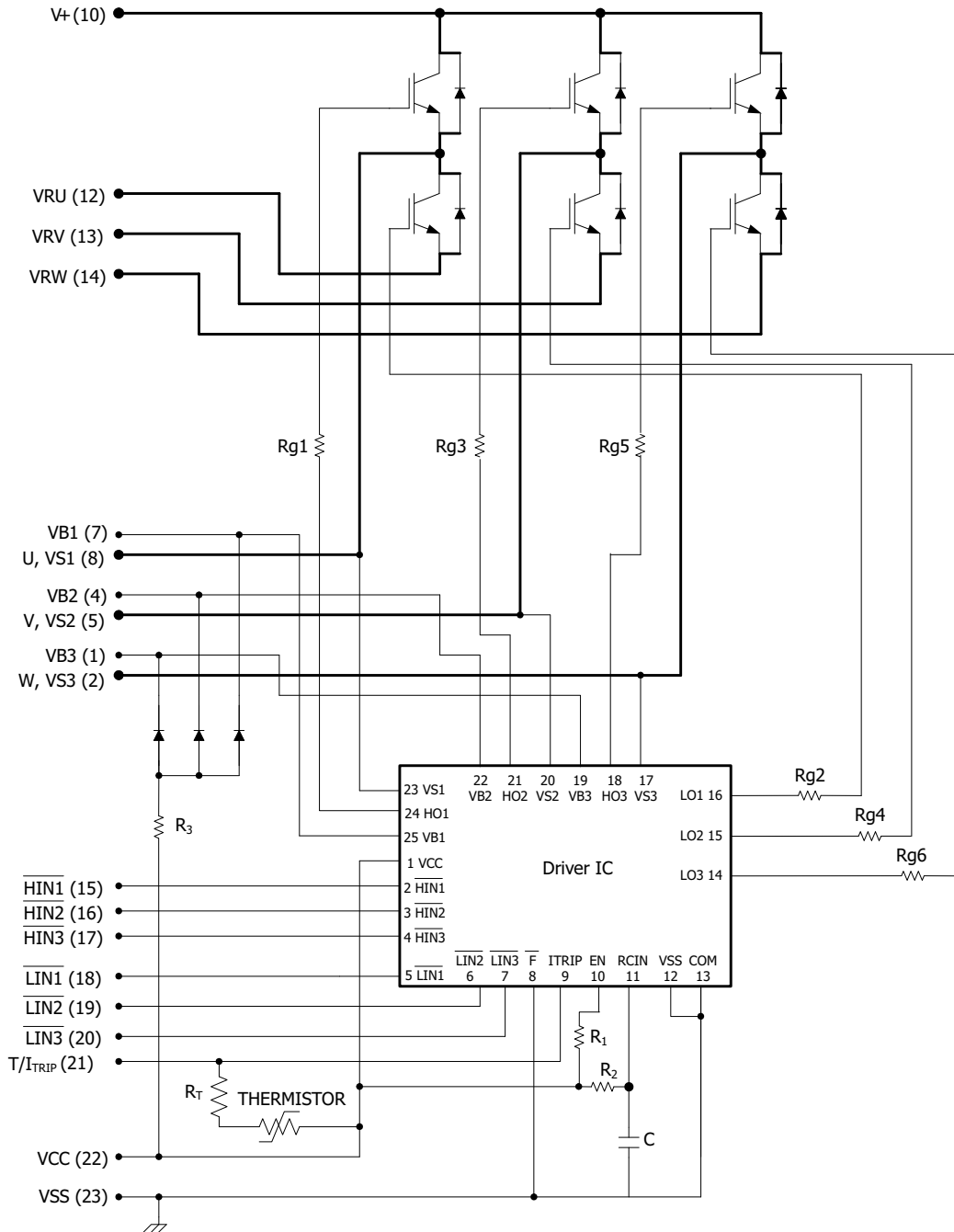
Parameter	Description	Value	Units
V_{CES} / V_{RRM}	IGBT/Diode Blocking Voltage	600	V
V^+	Positive Bus Input Voltage	450	
$I_O @ T_C=25^\circ\text{C}$	RMS Phase Current (Note 1)	16	A
$I_O @ T_C=100^\circ\text{C}$	RMS Phase Current (Note 1)	8	
I_O	Pulsed RMS Phase Current (Note 2)	30	
F_{PWM}	PWM Carrier Frequency	20	kHz
P_D	Power dissipation per IGBT @ $T_C = 25^\circ\text{C}$	31	W
V_{ISO}	Isolation Voltage (1min)	2000	V _{RMS}
T_J (IGBT & Diodes)	Operating Junction temperature Range	-40 to +150	°C
T_J (Driver IC)	Operating Junction temperature Range	-40 to +150	
T	Mounting torque Range (M3 screw)	0.5 to 1.0	Nm

Note 1: Sinusoidal Modulation at $V^+ = 400\text{V}$, $T_J = 150^\circ\text{C}$, $F_{PWM} = 16\text{kHz}$, Modulation Depth=0.8, PF=0.6, See Figure 3.

Note 2: $t_p < 100\text{ms}$; $T_C = 25^\circ\text{C}$; $F_{PWM} = 16\text{kHz}$. Limited by $I_{BUS-ITRIP}$, see Table "Inverter Section Electrical Characteristics"

IRAMX16UP60A

Internal Electrical Schematic - IRAMX16UP60A



Absolute Maximum Ratings (Continued)

All voltages are absolute referenced to COM

Symbol	Parameter	Min	Max	Units	Conditions
I_{BDF}	Bootstrap Diode Peak Forward Current	---	4.5	A	$t_p = 10\text{ms}$, $T_J = 150^\circ\text{C}$, $T_C = 100^\circ\text{C}$
$P_{BR \text{ Peak}}$	Bootstrap Resistor Peak Power (Single Pulse)	---	25.0	W	$t_p = 100\mu\text{s}$, $T_C = 100^\circ\text{C}$ ESR / ERJ series
$V_{S1,2,3}$	High side floating supply offset voltage	$V_{B1,2,3} - 25$	$V_{B1,2,3} + 0.3$	V	
$V_{B1,2,3}$	High side floating supply voltage	-0.3	600	V	
V_{CC}	Low Side and logic fixed supply voltage	-0.3	20	V	
V_{IN}, V_{EN}	Input voltage LIN, HIN, EN	-0.3	Lower of ($V_{SS} + 15\text{V}$) or $V_{CC} + 0.3\text{V}$	V	

Inverter Section Electrical Characteristics @ $T_J = 25^\circ\text{C}$

Symbol	Parameter	Min	Typ	Max	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	---	---	V	$V_{IN} = 5\text{V}$, $I_C = 250\mu\text{A}$
$\Delta V_{(BR)CES} / \Delta T$	Temperature Coeff. Of Breakdown Voltage	---	0.3	---	V/ $^\circ\text{C}$	$V_{IN} = 5\text{V}$, $I_C = 1.0\text{mA}$ ($25^\circ\text{C} - 150^\circ\text{C}$)
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	---	1.55	1.85	V	$I_C = 8\text{A}$, $V_{CC} = 15\text{V}$
		---	1.80	2.10		$I_C = 8\text{A}$, $V_{CC} = 15\text{V}$, $T_J = 150^\circ\text{C}$
I_{CES}	Zero Gate Voltage Collector Current	---	5	80	μA	$V_{IN} = 5\text{V}$, $V^+ = 600\text{V}$
		---	165	---		$V_{IN} = 5\text{V}$, $V^+ = 600\text{V}$, $T_J = 150^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	---	2.0	2.4	V	$I_C = 8\text{A}$
		---	1.4	1.9		$I_C = 8\text{A}$, $T_J = 150^\circ\text{C}$
V_{BDFM}	Bootstrap Diode Forward Voltage Drop	--	--	1.25	V	$I_F = 1\text{A}$
		---	---	1.10		$I_F = 1\text{A}$, $T_J = 125^\circ\text{C}$
R_{BR}	Bootstrap Resistor Value	---	22	---	Ω	$T_J = 25^\circ\text{C}$
$\Delta R_{BR} / R_{BR}$	Bootstrap Resistor Tolerance	---	---	± 5	%	$T_J = 25^\circ\text{C}$

Inverter Section Switching Characteristics @ $T_J = 25^\circ\text{C}$

Symbol	Parameter	Min	Typ	Max	Units	Conditions
E_{ON}	Turn-On Switching Loss	---	315	435	μJ	$I_C=8\text{A}$, $V^+=400\text{V}$ $V_{CC}=15\text{V}$, $L=2\text{mH}$ Energy losses include "tail" and diode reverse recovery
E_{OFF}	Turn-Off Switching Loss	---	150	180		
E_{TOT}	Total Switching Loss	---	465	615		
E_{REC}	Diode Reverse Recovery energy	---	30	60		
t_{RR}	Diode Reverse Recovery time	---	70	90	ns	See CT1
E_{ON}	Turn-on Switching Loss	---	500	700	μJ	$I_C=8\text{A}$, $V^+=400\text{V}$ $V_{CC}=15\text{V}$, $L=2\text{mH}$, $T_J=150^\circ\text{C}$ Energy losses include "tail" and diode reverse recovery
E_{OFF}	Turn-off Switching Loss	---	270	335		
E_{TOT}	Total Switching Loss	---	770	1035		
E_{REC}	Diode Reverse Recovery energy	---	60	100		
t_{RR}	Diode Reverse Recovery time	---	120	150	ns	See CT1
Q_G	Turn-On IGBT Gate Charge	---	56	84	nC	$I_C=15\text{A}$, $V^+=400\text{V}$, $V_{GE}=15\text{V}$
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				$T_J=150^\circ\text{C}$, $I_C=45\text{A}$, $V_P=600\text{V}$ $V^+=450\text{V}$ $V_{CC}=+15\text{V}$ to 0V See CT3
SCSOA	Short Circuit Safe Operating Area	10	---	---	μs	$T_J=150^\circ\text{C}$, $V_P=600\text{V}$, $V^+=360\text{V}$, $V_{CC}=+15\text{V}$ to 0V See CT2
I_{CSC}	Short Circuit Collector Current	---	140	---	A	$T_J=150^\circ\text{C}$, $V_P=600\text{V}$, $t_{SC}<10\mu\text{s}$ $V^+=360\text{V}$, $V_{GE}=15\text{V}$ $V_{CC}=+15\text{V}$ to 0V See CT2

Recommended Operating Conditions Driver Function

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. All voltages are absolute referenced to COM. The V_S offset is tested with all supplies biased at 15V differential (Note 3)

Symbol	Definition	Min	Max	Units
$V_{B1,2,3}$	High side floating supply voltage	V_S+12	V_S+20	V
$V_{S1,2,3}$	High side floating supply offset voltage	Note 4	450	
V_{CC}	Low side and logic fixed supply voltage	12	20	V
$V_{T/ITRIP}$	T/I_{TRIP} input voltage	V_{SS}	$V_{SS}+5$	
V_{IN}	Logic input voltage LIN, HIN	V_{SS}	$V_{SS}+5$	V

Note 3: For more details, see IR21365 data sheet

Note 4: Logic operational for V_S from COM-5V to COM+600V. Logic state held for V_S from COM-5V to COM- V_{BS} . (please refer to DT97-3 for more details)

Static Electrical Characteristics Driver Function

V_{BIAS} (V_{CC} , $V_{BS1,2,3}$)=15V, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to all six channels. (Note 3)

Symbol	Definition	Min	Typ	Max	Units
V_{IH}	Logic "0" input voltage	3.0	---	---	V
V_{IL}	Logic "1" input voltage	---	---	0.8	V
V_{CCUV+} , V_{BSUV+}	V_{CC} and V_{BS} supply undervoltage Positive going threshold	10.6	11.1	11.6	V
V_{CCUV-} , V_{BSUV-}	V_{CC} and V_{BS} supply undervoltage Negative going threshold	10.4	10.9	11.4	V
V_{CCUVH} , V_{BSUVH}	V_{CC} and V_{BS} supply undervoltage lock-out hysteresis	---	0.2	---	V
$V_{IN, Clamp}$	Input Clamp Voltage (HIN, LIN, T/I _{TRIP}) $I_{IN}=10\mu A$	4.9	5.2	5.5	V
I_{QBS}	Quiescent V_{BS} supply current $V_{IN}=0V$	---	---	165	μA
I_{QCC}	Quiescent V_{CC} supply current $V_{IN}=0V$	---	---	3.35	mA
I_{LK}	Offset Supply Leakage Current	---	---	60	μA
I_{IN+}	Input bias current $V_{IN}=5V$	---	200	300	μA
I_{IN-}	Input bias current $V_{IN}=0V$	---	100	220	μA
T/I_{TRIP+}	T/I _{TRIP} bias current $V_{ITRIP}=5V$	---	30	100	μA
T/I_{TRIP-}	T/I _{TRIP} bias current $V_{ITRIP}=0V$	---	0	1	μA
$V(T/I_{TRIP})$	T/I _{TRIP} threshold Voltage	3.85	4.30	4.75	V
$V(T/I_{TRIP}, HYS)$	T/I _{TRIP} Input Hysteresis	---	0.07	---	V

Dynamic Electrical Characteristics

Driver only timing unless otherwise specified.

Symbol	Parameter	Min	Typ	Max	Units	Conditions
T_{ON}	Input to Output propagation turn-on delay time (see fig.11)	---	590	---	ns	$V_{CC}=V_{BS}= 15V$, $I_C=8A$, $V^+=400V$
T_{OFF}	Input to Output propagation turn-off delay time (see fig. 11)	---	660	---	ns	
T_{FLIN}	Input Filter time (HIN, LIN)	100	200	---	ns	$V_{IN}=0$ & $V_{IN}=5V$
$T_{BLT-Trip}$	I_{TRIP} Blanking Time	100	150	---	ns	$V_{IN}=0$ & $V_{IN}=5V$
D_T	Dead Time ($V_{BS}=V_{DD}=15V$)	220	290	360	ns	$V_{BS}=V_{CC}=15V$
M_T	Matching Propagation Delay Time (On & Off)	---	40	75	ns	$V_{CC}= V_{BS}= 15V$, external dead time> 400ns
T_{ITrip}	I_{Trip} to six switch to turn-off propagation delay (see fig. 2)	---	---	1.75	μs	$V_{CC}=V_{BS}= 15V$, $I_C=8A$, $V^+=400V$
$T_{FLT-CLR}$	Post I_{Trip} to six switch to turn-off clear time (see fig. 2)	---	7.7	---	ms	$T_C = 25^\circ C$
		---	6.7	---		$T_C = 100^\circ C$

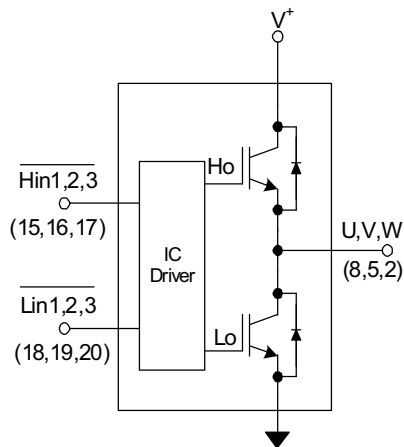
Thermal and Mechanical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Conditions
$R_{th(J-C)}$	Thermal resistance, per IGBT	---	3.5	4.0	°C/W	Flat, greased surface. Heatsink compound thermal conductivity 1W/mK
$R_{th(J-C)}$	Thermal resistance, per Diode	---	5.0	5.5		
$R_{th(C-S)}$	Thermal resistance, C-S	---	0.1	---		
C_D	Creepage Distance	3.2	---	---	mm	See outline Drawings

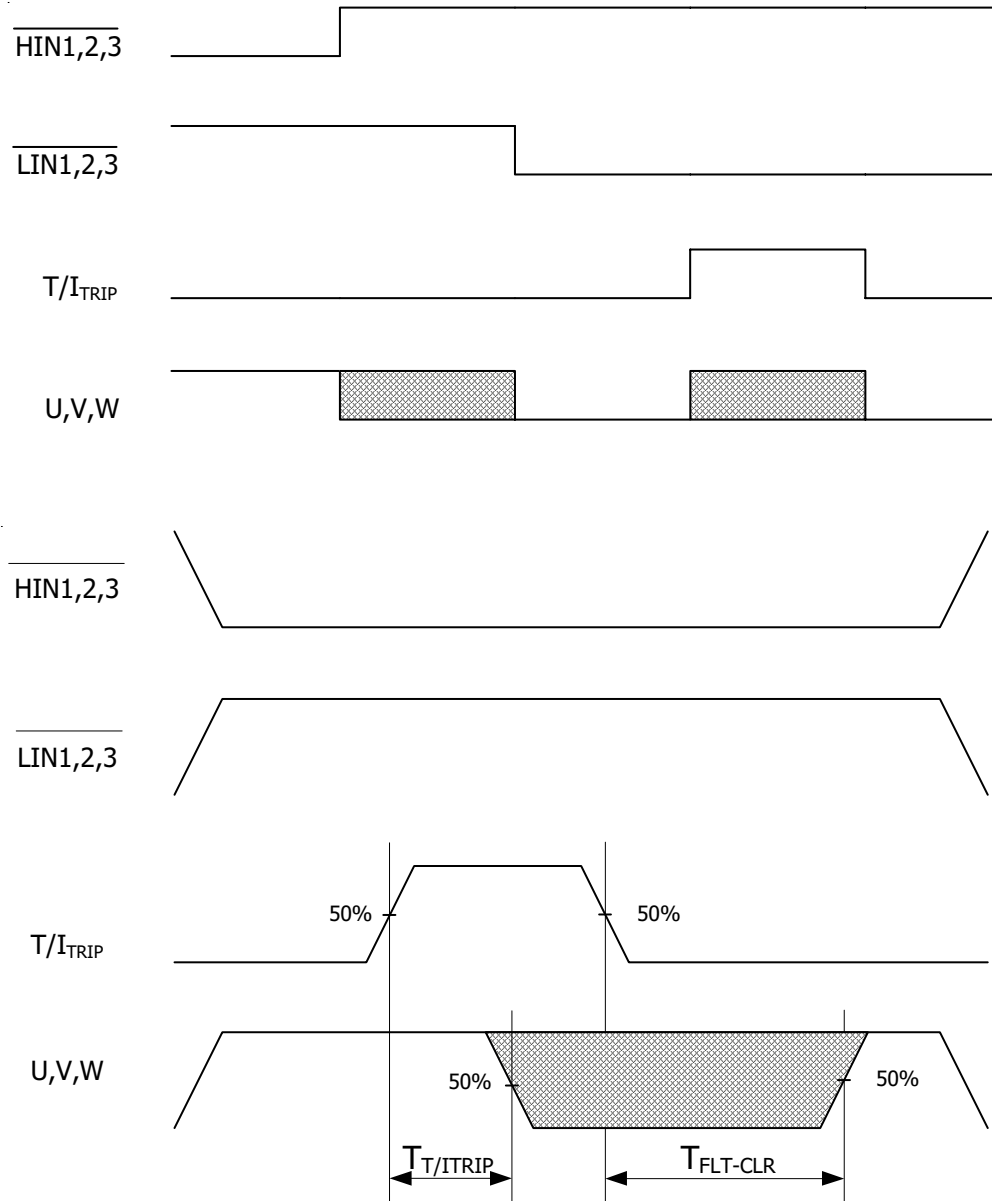
Internal NTC - Thermistor Characteristics

Parameter	Definition	Min	Typ	Max	Units	Conditions
R_{25}	Resistance	97	100	103	k Ω	$T_C = 25^\circ\text{C}$
R_{125}	Resistance	2.25	2.52	2.80	k Ω	$T_C = 125^\circ\text{C}$
B	B-constant (25-50°C)	4165	4250	4335	k	$R_2 = R_1 e^{[B(1/T_2 - 1/T_1)]}$
Temperature Range		-40		125	°C	
Typ. Dissipation constant			1		mW/°C	$T_C = 25^\circ\text{C}$

Input-Output Logic Level Table



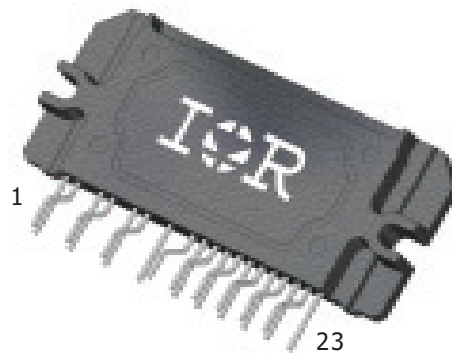
FLT- EN	I_{TRIP}	$\overline{HIN1,2,3}$	$\overline{LIN1,2,3}$	U,V,W
1	0	0	1	V^+
1	0	1	0	0
1	0	1	1	Off
1	1	X	X	Off
0	X	X	X	Off



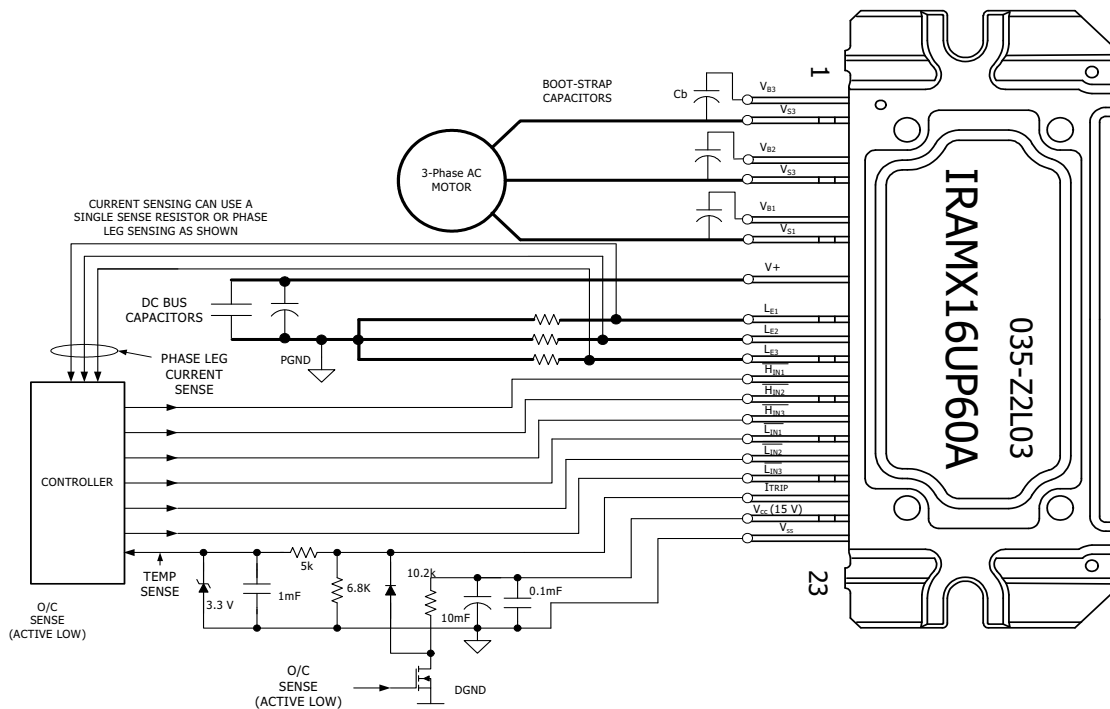
Note 5: The shaded area indicates that both high-side and low-side switches are off and therefore the half-bridge output voltage would be determined by the direction of current flow in the load.

Module Pin-Out Description

Pin	Name	Description
1	V_{B3}	High Side Floating Supply Voltage 3
2	W, V_{S3}	Output 3 - High Side Floating Supply Offset Voltage
3	NA	none
4	V_{B2}	High Side Floating Supply voltage 2
5	V, V_{S2}	Output 2 - High Side Floating Supply Offset Voltage
6	NA	none
7	V_{B1}	High Side Floating Supply voltage 1
8	U, V_{S1}	Output 1 - High Side Floating Supply Offset Voltage
9	NA	none
10	V^+	Positive Bus Input Voltage
11	NA	none
12	L_{E1}	Low Side Emitter Connection - Phase 1
13	L_{E2}	Low Side Emitter Connection - Phase 2
14	L_{E3}	Low Side Emitter Connection - Phase 3
15	\overline{H}_{IN1}	Logic Input High Side Gate Driver - Phase 1
16	\overline{H}_{IN2}	Logic Input High Side Gate Driver - Phase 2
17	\overline{H}_{IN3}	Logic Input High Side Gate Driver - Phase 3
18	\overline{L}_{IN1}	Logic Input Low Side Gate Driver - Phase 1
19	\overline{L}_{IN2}	Logic Input Low Side Gate Driver - Phase 2
20	\overline{L}_{IN3}	Logic Input Low Side Gate Driver - Phase 3
21	T/I_{TRIP}	Temperature Monitor and Shut-down Pin
22	V_{CC}	+15V Main Supply
23	V_{SS}	Negative Main Supply



Typical Application Connection IRAMX16UP60A



1. Electrolytic bus capacitors should be mounted as close to the module bus terminals as possible to reduce ringing and EMI problems. Additional high frequency ceramic capacitor mounted close to the module pins will further improve performance.
2. In order to provide good decoupling between V_{CC}-V_{SS} and V_{B1,2,3}-V_{S1,2,3} terminals, the capacitors shown connected between these terminals should be located very close to the module pins. Additional high frequency capacitors, typically 0.1μF, are strongly recommended.
3. Value of the boot-strap capacitors depends upon the switching frequency. Their selection should be made based on IR design tip DN 98-2a, application note AN-1044 or Figure 9. Bootstrap capacitor value must be selected to limit the power dissipation of the internal resistor in series with the V_{CC}. (see maximum ratings Table on page 3).
4. After approx. 8ms the FAULT is reset. (see Dynamic Characteristics Table on page 5).
5. PWM generator must be disabled within Fault duration to guarantee shutdown of the system, overcurrent condition must be cleared before resuming operation.

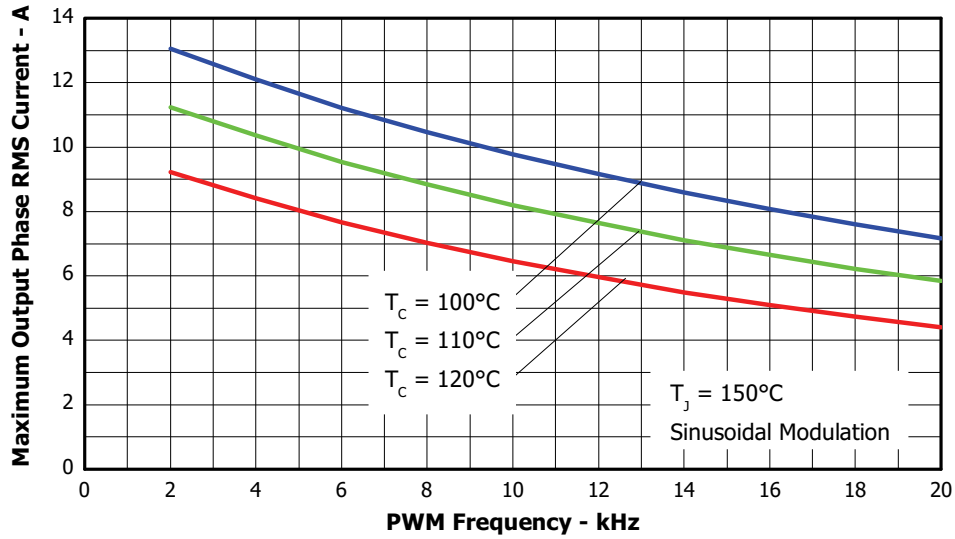


Figure 3. Maximum Sinusoidal Phase Current vs. PWM Switching Frequency
 $V^+=400\text{V}$, $T_j=150^\circ\text{C}$, Modulation Depth=0.8, PF=0.6

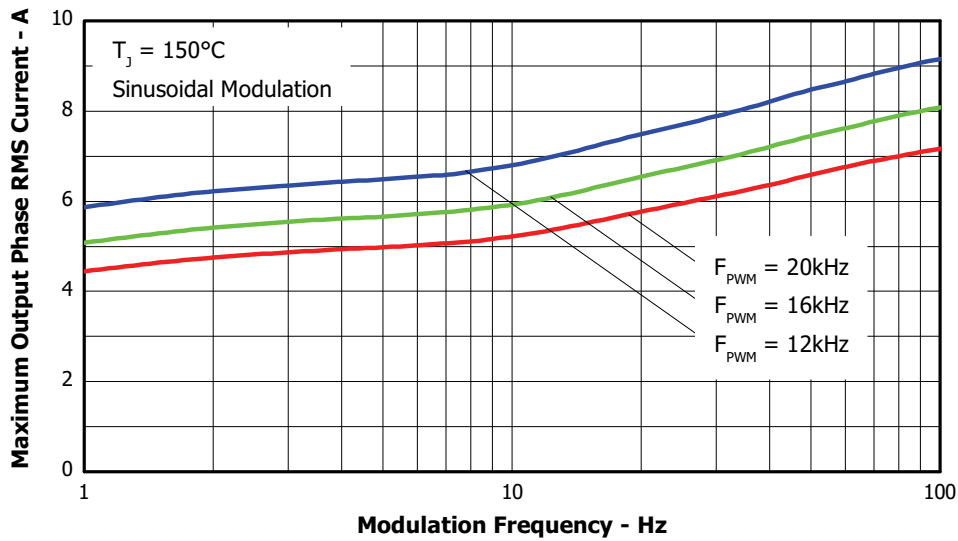


Figure 4. Maximum Sinusoidal Phase Current vs. Modulation Frequency
 $V^+=400\text{V}$, $T_j=150^\circ\text{C}$, $T_c=100^\circ\text{C}$, Modulation Depth=0.8, PF=0.6

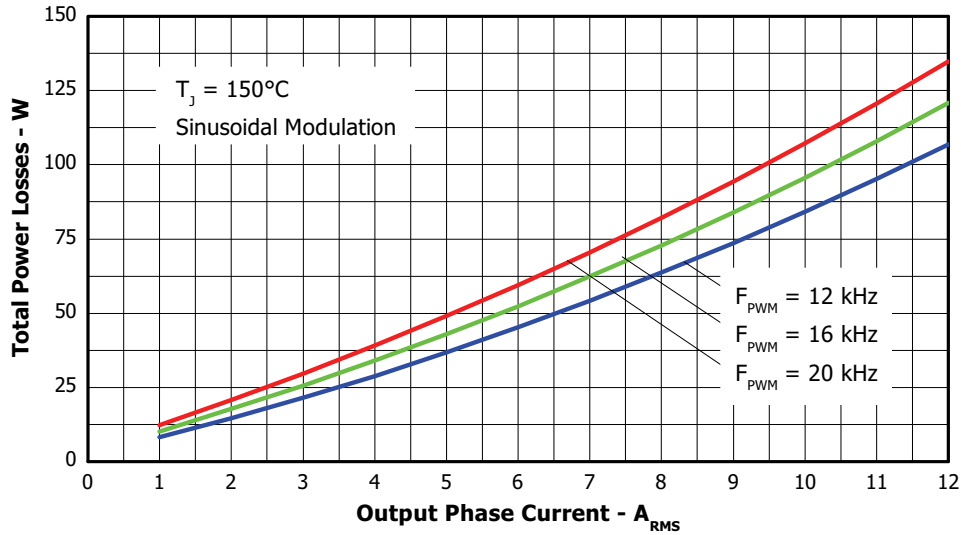


Figure 5. Total Power Losses vs. PWM Switching Frequency, Sinusoidal modulation
 $V^+ = 400V$, $T_J = 150^\circ C$, Modulation Depth=0.8, PF=0.6

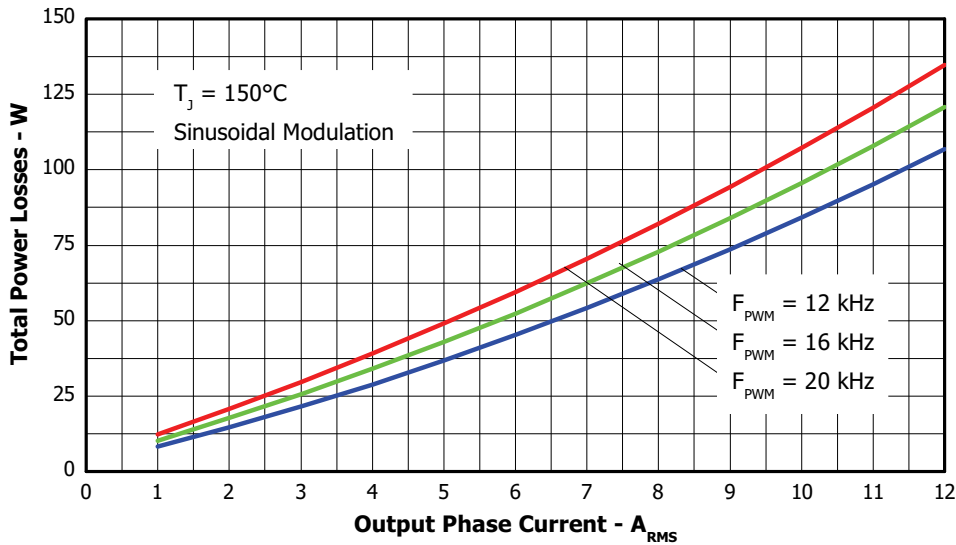


Figure 6. Total Power Losses vs. Output Phase Current, Sinusoidal modulation
 $V_{BUS} = 400V$, $T_J = 150^\circ C$, Modulation Depth=0.8, PF=0.6

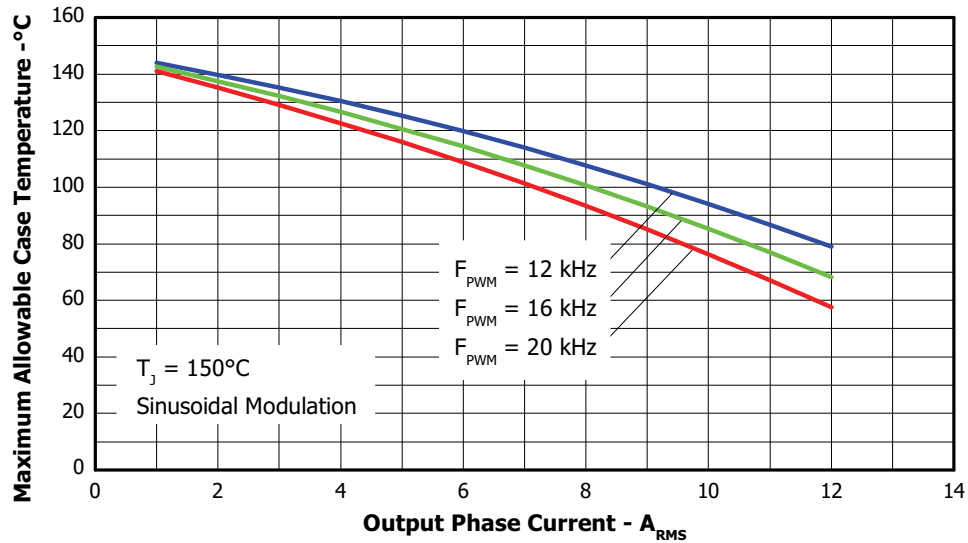


Figure 7. Maximum Allowable Case temperature vs. Output RMS Current per Phase

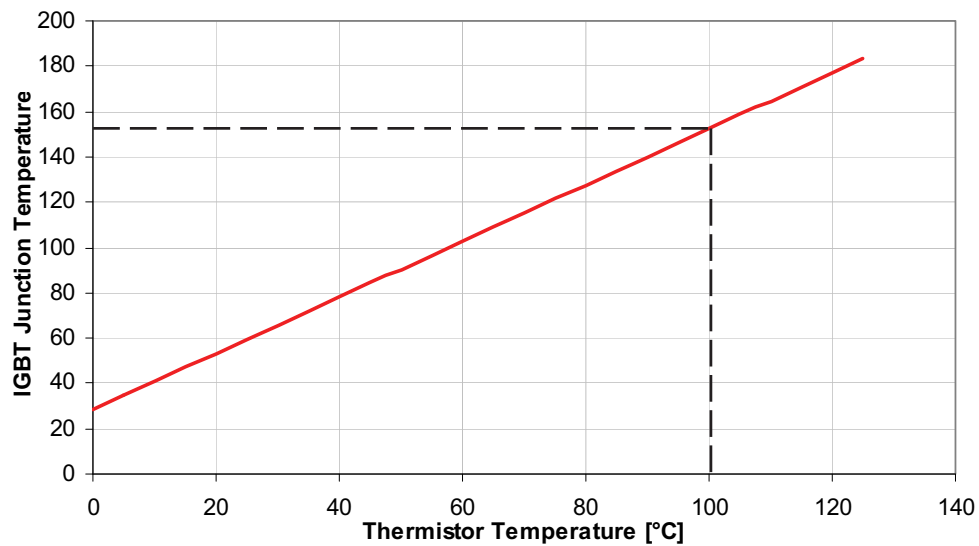


Figure 8. Estimated Maximum IGBT Junction Temperature vs. Thermistor Temperature

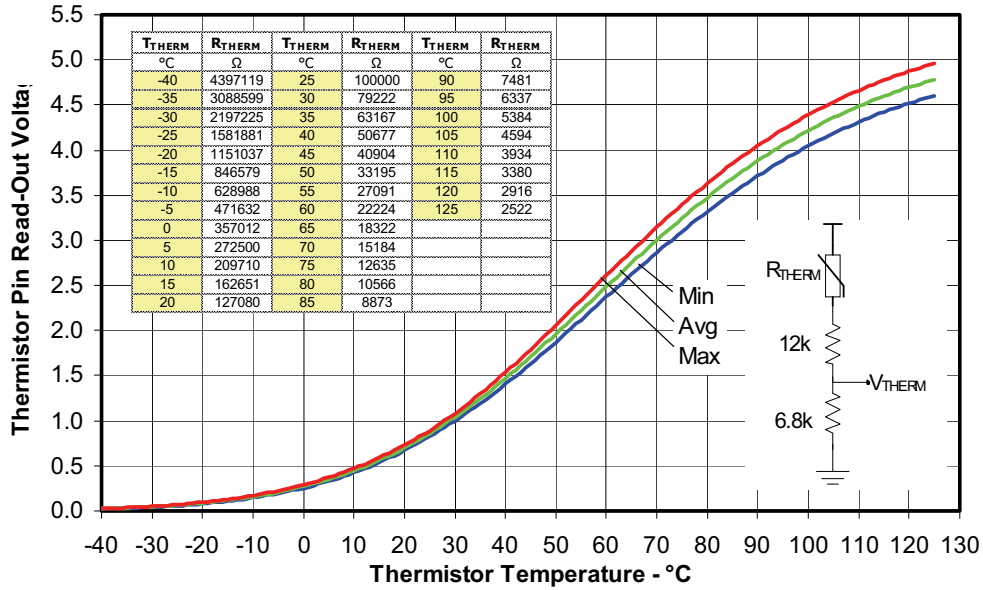


Figure 9. Thermistor Readout vs. Temperature (6.8kohm, 1% pull down resistor) and Nominal Thermistor Resistance values vs. Temperature Table.

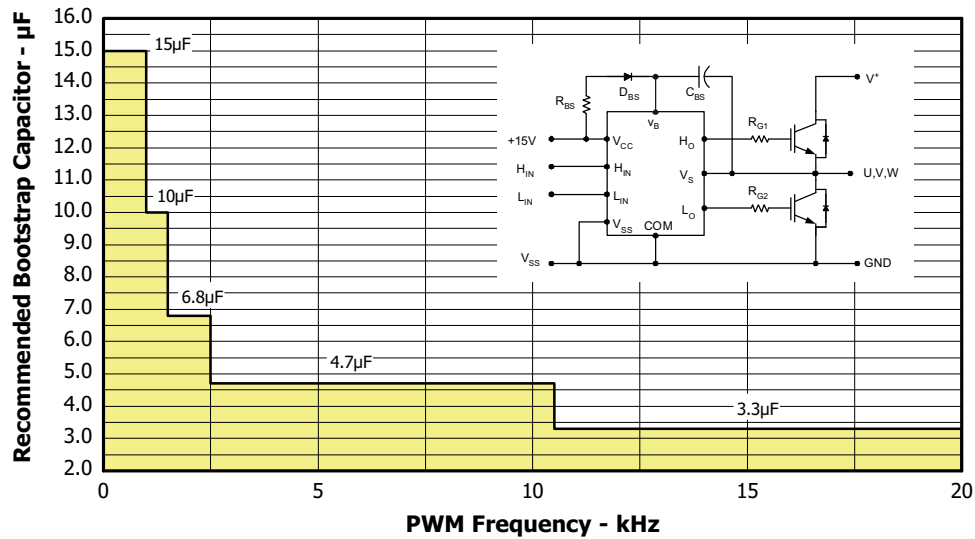


Figure 10. Recommended Bootstrap Capacitor Value vs. Switching Frequency

Figure 11. Switching Parameter Definitions

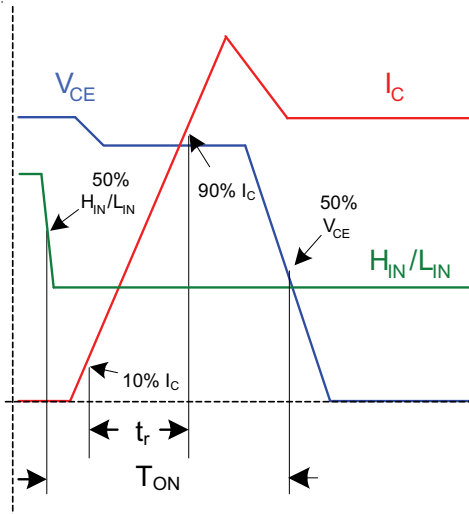


Figure 11a. Input to Output Propagation turn-on Delay Time

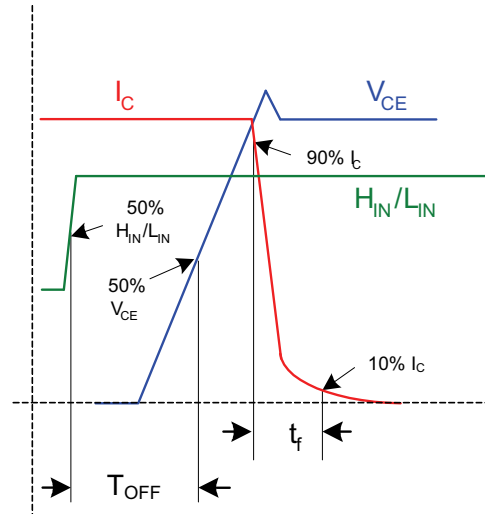


Figure 11b. Input to Output Propagation turn-off Delay Time

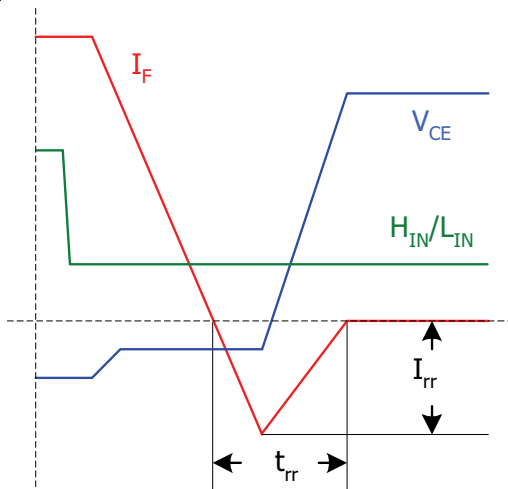


Figure 11c. Diode Reverse Recovery

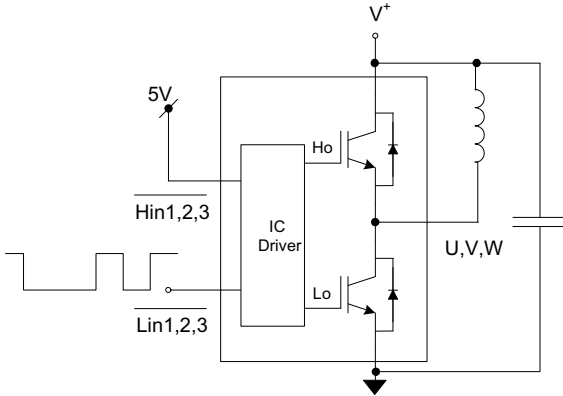


Figure CT1. Switching Loss Circuit

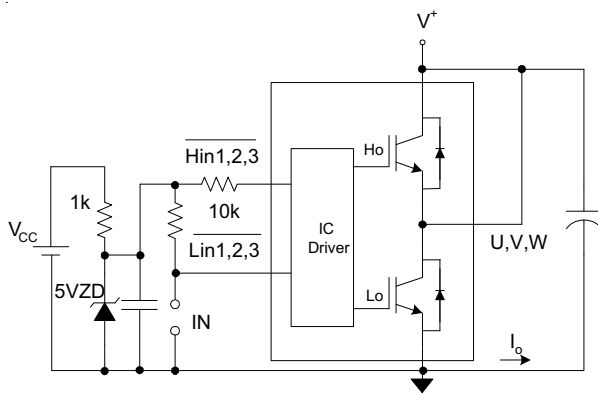
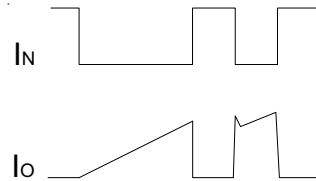


Figure CT2. S.C.SOA Circuit

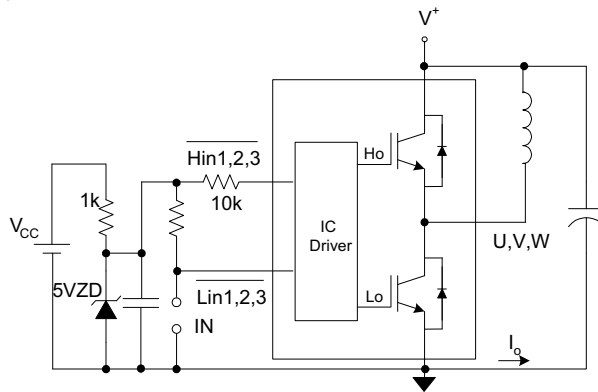
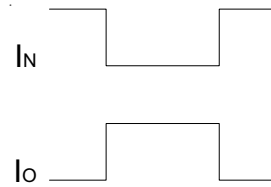
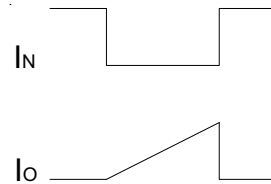


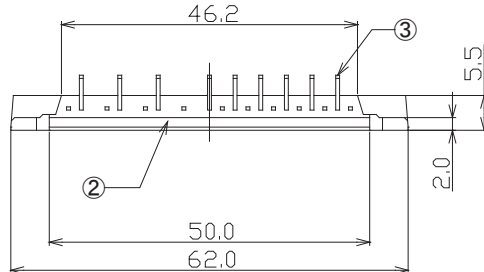
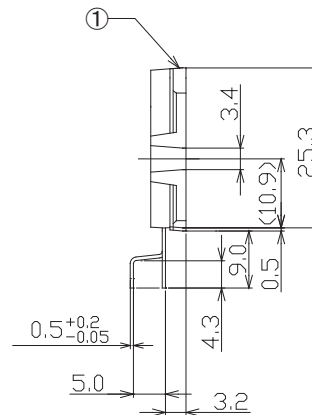
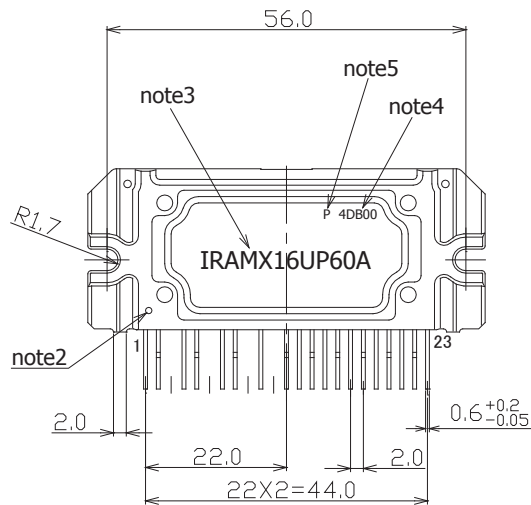
Figure CT3. R.B.SOA Circuit



IRAMX16UP60A

Package Outline IRAMX16UP60A

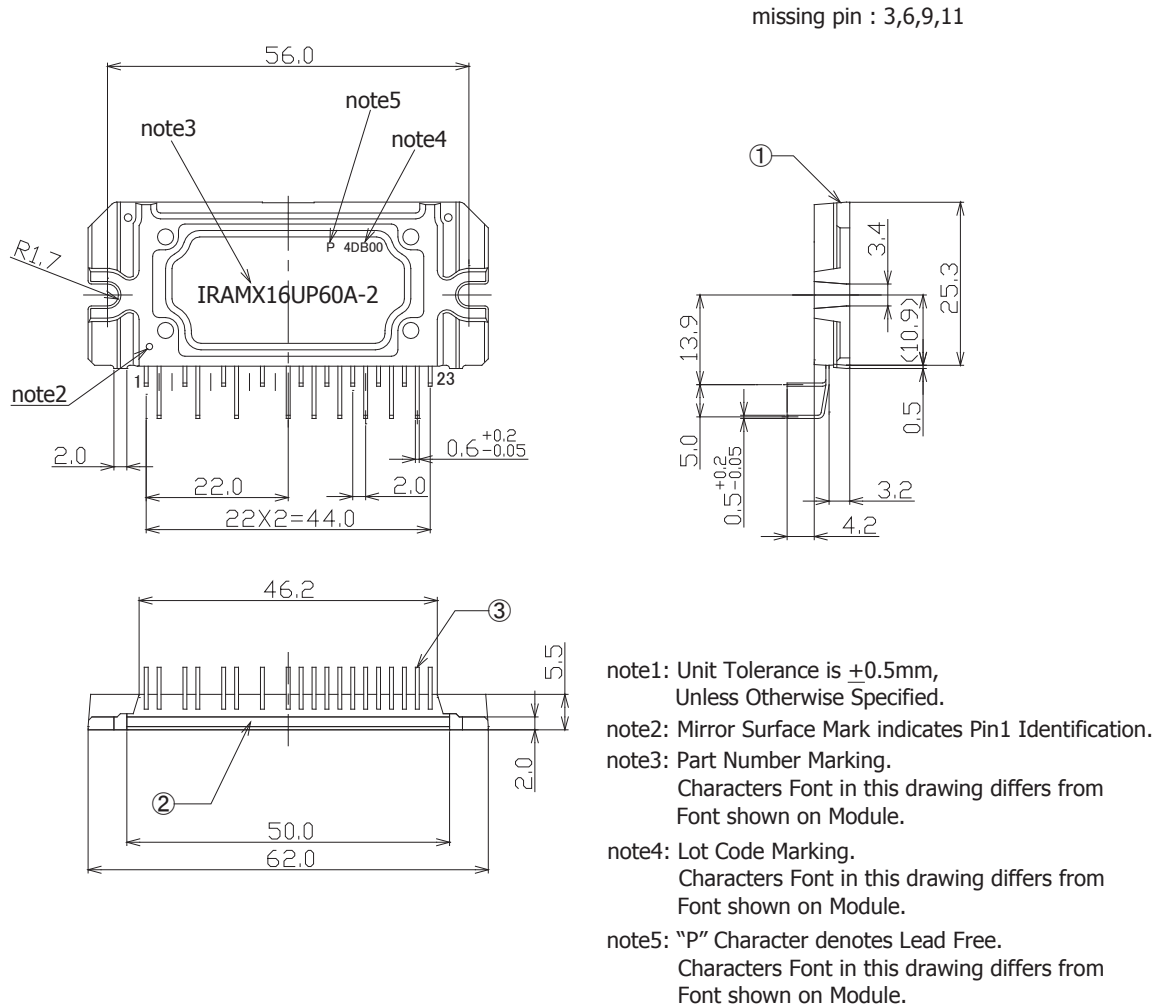
missing pin : 3,6,9,11



- note1: Unit Tolerance is ± 0.5 mm, Unless Otherwise Specified.
- note2: Mirror Surface Mark indicates Pin1 Identification.
- note3: Part Number Marking. Characters Font in this drawing differs from Font shown on Module.
- note4: Lot Code Marking. Characters Font in this drawing differs from Font shown on Module.
- note5: "P" Character denotes Lead Free. Characters Font in this drawing differs from Font shown on Module.

Dimensions in mm
 For mounting instruction see AN-1049

Package Outline IRAMX16UP60A-2



Dimensions in mm
 For mounting instruction see AN-1049